

EPOXY

5 Strengths of Coating Type	5 Weaknesses of Cure Type
<ul style="list-style-type: none">• Useful to about 150fC [302fF]• Harder durometer, abrasion resistance• CTE closer to epoxy PCB substrate• Higher T g• Good dielectric properties	Solvent Evaporation <ul style="list-style-type: none">• Higher chloride contamination potential• Process intensive, difficult to maintain viscosity, complex mix ratios• Potential for high stress during temperature cycling conditions• Difficult to rework• High probability of reversion under temperature and humidity stress conditions
	Heat Cure <ul style="list-style-type: none">• Cure is dependent on thickness• Component mass affects time and temperature of cure process• Selective coating quality (edge definition) could be impacted• Shrinkage (3% – 10%), potential for damaging fragile (e.g., glass) components• Should be used with caution for low temperature components
	UV Cure <ul style="list-style-type: none">• One component coatings require accurate application material to avoid shadowed areas• Two part systems require meter mix equipment• Some coatings are more difficult to rework• UV Intensity and Wavelength effects cure• Some secondary cure mechanisms require heat exposure
	Catalyzed <ul style="list-style-type: none">• Cure inhibition• Short work life• Contamination sensitive• Difficult to rework• Pungent odor